



Silicom *ThunderFjord* - FPGA SmartNIC FB2CDG1@AGM39D-2

Dual port QSFPDD56, 2x400 GE, PCIe Gen5 x16, Intel® Agilex™ M-series FPGA Based, up to 32GB HBM2e with 2xARC6-16 connector (16x28 Gbps), for Ethernet, PCIe or interconnect

Product Description

The Silicom *ThunderFjord B* is a high-performance programmable PCIe Server adapter based on the Altera® Agilex™ M-series AGMF039 FPGA (option for AGMF032).

The Altera Agilex-M™ is an extremely powerful FPGA which also features up to on-chip 32GB HBM2e memory providing an unprecedented 2 x 2.6 Tbps HBM2e bandwidth. The combination of lightning fast logic and equally fast memory ensures a platform that can deliver. The ThunderFjord can also be offered with FPGA models without HBM2e.

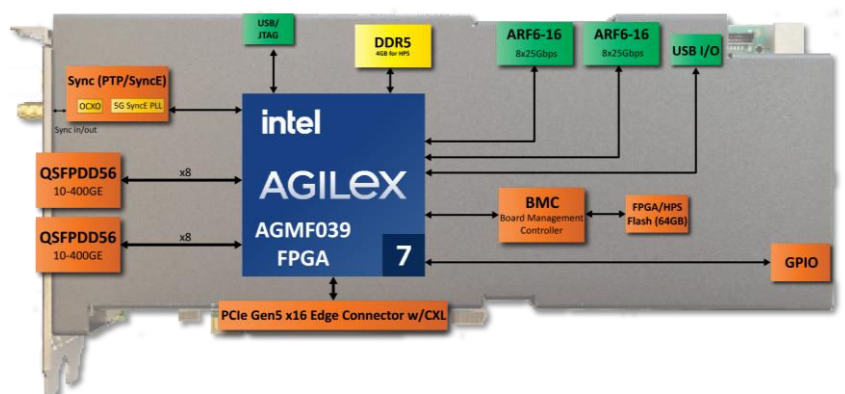
The card is equipped with 2 x QSFPDD56 for supporting 2x 400GE, as well as a wide range of other link speed combinations like 16x10/25GE or even 8x100G with the appropriate breakout modules.

The *ThunderFjord* features 2 x AcceleRate® Slim Cable Assembly (ARC6) connectors with 2x 8x28Gbps from Samtec. The ARC6 connectors add unprecedented flexibility in host bandwidth and network connectivity. Silicom offers an adaptor an additional PCIe Gen4 x16 connector that can be employed for additional host bandwidth. The same connectors can alternatively be used with Firefly™ flyover cables for connecting additional 2x 8xFSFP28 or 2x 2xQSF28 for higher Ethernet link capacity to the solution in appliances. Silicom offers a 4xQSF28 bracket for easy utilization of the expansion option. The AR6-16 can alternatively be used for direct connection of two boards, connect multiple cards in series or daisy chain, or connect to other products with suitable interface.

The AGM FPGA series features CXL 1.1 and 2.0, providing heterogeneous processing and computing in performance-intensive workloads like AI, machine learning and analytics. Additionally, the AGM FPGA device includes Quad-core 64 bit Arm Cortex A53 processor.

Key Use Cases for ThunderFjord

- **Network Security & Telemetry**
 - Virtual Firewall (vFW)
 - DDoS Mitigation
 - IDS/IPS function
 - IP Security (IPsec)
 - Transport Layer Security (TLS)
 - Packet monitoring and analytics
- **Network Functions**
 - 5G/6G User Plane Function (UPF)
 - 5G Access Gateway Function (AGF)
 - Virtual Broadband Network Gateway (vBNG)
 - Virtual Application Delivery Controller
 - Carrier Grade Network Address Translation
 - Cloud Gateway
 - Application Access Gateway
- **Application acceleration**
 - AI/ML inference offload
 - Data analysis offload
 - Sensor aggregation and analysis
 - Sensor recording



Key Features of ThunderFjord

- Intel® Agilex™ AGMF039 FPGA with Quad-core 64 bit Arm Cortex A53 processor
- 2 x QSFPDD56 ports
- HBM2e options: 32GB, 16BG, No HBM2e
- 2 x AcceleRate® Slim Cable Assembly (ARC6) expansion connectors each with 8x28Gbps
- PCIe x16 Gen5 w/CXL
- 5G SyncE PLL with Silicom TimeSync Solution (STS)
- Dedicated 4GB DDR5 ECC RAM for HPS
- USB/JTAG connector
- GPIO
- Intel® Max® 10 Board Management Controller
- 1 x PPS/10MHz SMA connector
- Dual slot passive heat sink (single slot optional)
- On-board power and temperature sensors
- FPGA controlled link and status LEDs

ThunderFjord expansion use cases

Silicom ThunderFjord provides high capacity and high speed expansion options. The card comes with 2 ARC6-16 connectors each providing 8 x 28 Gbps high speed I/O. Along with an internal flat cable side band signals supporting the High speed I/O expansion options and use cases.

On the PCB, the ARC6-16 connectors are routed to the FPGA on an F-Tile's 16 channels at 32 Gbps (NRZ). Being connected to an F-tile allows for the Highspeed IO to be used with the tiles Hard IPs, such as

- 400 GbE hard IP block (10/25/50/100/200/400 GbE FEC/PCS/MAC)
- PCI Express* (PCIe*) hard IP block (4.0 x16)

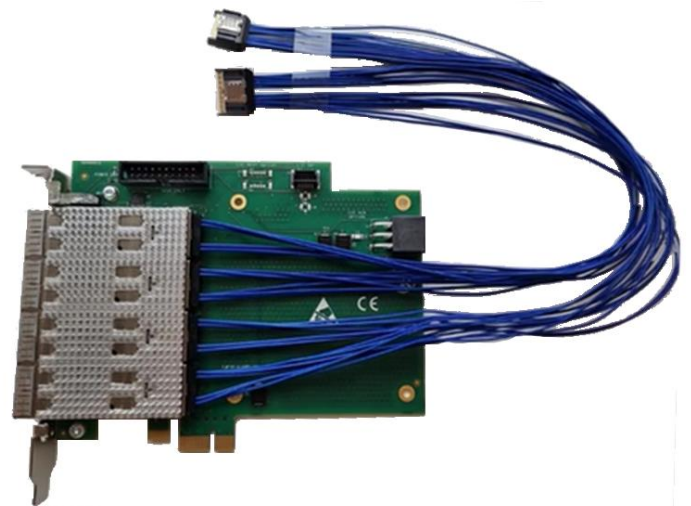


This allows for easy and standardized expansion for the host system internally or externally

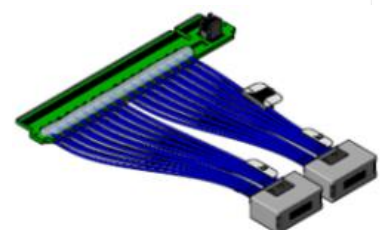
Using ARC6-16 connector cables in the onboard ARC6-16 sockets, the high speed I/O can be used for interfacing with card external devices or systems.

The ARC-6 cables can be provided in custom lengths and have the great advantage that the cables are highly flexible yet still securely shielded and very robust. Fitting the expansion options in servers is very easy due to the very flexible cables

Silicom and Samtec have designed and produce cable assemblies with ARC6-16 connectors specifically for operation with Silicom ThunderFjord card, utilizing the Samtec Flyover® cable technology. Silicom offers Samtec flyover cable assemblies for 8x25GE FSFP28 and for 2x100GE QSF28 for device integration. The 2x100GE QSF28 is utilized in an PCB/assembly offered by Silicom where 2 of the 2x100GE QSF28 cable assemblies are mounted on a PCI compliant PCB with bracket and AUX power. This allows for easy expansion with 4 extra QSFP28 ports in spare PCI slot using ThunderFjord's 2xARC&-16 connectors. An actual PCI slot is not required as the card can be powered via AUX power cable, and there no need for the PCI slot for any signaling. The ports are fully controlled by the ThunderFjord FPGA.



With the adaptor offered the ThunderFjord provide QSFP-DDs for 400GE along-side 4xQSFP28s for extra 4x100GE or 16x10/25GE via breakout cables ensuring additional Ethernet bandwidth and high port and speed flexibility.



Additionally, Silicom and Samtec have designed a PCIe Gen4 x16 expansion cable adaptor connecting to the ThunderFjord's 2xARC6-16 in unison. Utilizing all 16x28Gbps channels provided to extend the PCIe Gen4 connectivity of the FPGA's F-tile to connect to host or other device providing a standard PCIe Gen4 x16 socket

Technical Specifications

Network Interface	
IEEE standard	IEEE 802.3 400GE, 200GE, 100GE, 25GE, 10GbE
Interfaces	<ul style="list-style-type: none"> ▪ Physical interface: 2 x QSFPDD56 slots ▪ Multimode SR4/SR8 (850nm), Single Mode LR4/LR8 (1310nm) or DAC (Twinax) ▪ Data rate: 2x400, 4x200, 2x200, 1x400, 4x100, 8x100G via CU DAC, 16x25, 16x10 GE ▪ Optional ARC-6 expansion: 4xQSFP28 (4x100GE) PCI adaptor (no PCI slot requirement) ▪ Optional ARC-6 expansion: Two 2xFlyover-QSFP28 cable assembly (4x100GE max) ▪ Optional ARC-6 expansion: Two 8xFlyover-SFP28 cable assembly (16x10/25GE max)
Host Interface	
PCI bus	<ul style="list-style-type: none"> ▪ PCIe 5.0 x16 ▪ Optional ARC-6 expansion: PCI Gen4 x16 cable assembly
General Technical Specifications	
FPGA Details	<p>Intel® Agilex™ AGMF039 (AGMF032 option)</p> <ul style="list-style-type: none"> ▪ R47A package, with 3 x F and 1 x R tile ▪ Fabric speed grade -2, Transceiver Speedgrade -1 for CXL support ▪ Quad-core 64 bit Arm Cortex*-A53 ▪ 32GB HBM2e, 16GB option, No HBM2e option ▪ 3 x 600GE HIPs (F-tiles), 2 for front ports, 1 usable for expansion connectors
Configuration	<ul style="list-style-type: none"> ▪ Configuration flash can be made to support multiple boot images with automatic fallback to factory default image ▪ Upload of FPGA configuration to flash via PCIe – with supporting image and tool
On-chip Memory	<ul style="list-style-type: none"> ▪ HBM2e, 32GB in Agilex™ M-series FPGA
On-board Memory	<ul style="list-style-type: none"> ▪ DDR5, 4GB ECC for HPS
Expansion Connectors	<ul style="list-style-type: none"> ▪ 2 x 32pin ARC6-16 connector for 2x 8x28Gbps <ul style="list-style-type: none"> ○ Expand with additional network ports <ul style="list-style-type: none"> ▪ via Silicom 4xFQSFP28 adaptors ▪ via up to 2x 8x28Gbps Flyover SFP28 cables ○ Allows an extra x16 PCIe Gen4 via adapter for extra Host PCI BW and resources ○ Interconnect with other products, in P2P or daisy chain configuration
On-board Clock	<ul style="list-style-type: none"> ▪ PCIe clock: 100 MHz ▪ DPLL ZL30793 ▪ Jitter cleaner ▪ 8 output reprogrammable clock generator (PLL) with SyncE support ▪ Optional expansion via secondary bracket with 4x SMA connector (PPS/10MHz/In/Out)
Additional Board Support	<ul style="list-style-type: none"> ▪ On-board power and temperature sensors (via SMBus/I2C) ▪ LEDs for board status and board management
Physical Dimensions	<ul style="list-style-type: none"> ▪ Weight: ~1600 g ▪ Full height, 123.4 mm ▪ ¾ length, 254.0 mm (+bracket) ▪ Dual slot
Environment	<ul style="list-style-type: none"> ▪ Storage temperature: -10C to 60C ▪ Operating temperature: 0C to 40C ▪ Hardware compliance: RoHS, FCC Class A, CE, UL
Thermal Design	<ul style="list-style-type: none"> ▪ Passive dual heat sink ▪ Passive single slot heat sink maybe provided. <p>Reduces thermal capacity, limiting processing capacity</p>

Power/TDP	<ul style="list-style-type: none"> Max power (TDP) 225 W, with standard server airflow for cooling Typical power consumption 100W – 150W The combined server-PCIe card solution may be limited in average power consumption by thermal constraints. Maximum supported is higher than TDP if adequate cooling is provided. Typical use case is fully dependent on FPGA implementation. High power connector 2x6 with 4 sideband signals for PCI AUX power (PCIe GEM 5.1) 65 W max from the PCIe slot, 345 W max from the 12V high power Aux connector *) (including optical modules)
Port LEDs	<ul style="list-style-type: none"> 2 x Link/ ACT for the 2 x QSFPDD56, on bracket 1 x multi color status LED, on bracket
Time Synchronization	<ul style="list-style-type: none"> Silicom TimeSync Solution (STS) IEEE 1588-2019, G8273.2, G8273.4 (T-BC/T-TSC), G8262(SyncE) 1 x PPS In/Out, 10Mhz In/Out (optional) DPLL ZL30793 OCXO PTP stack: LinuxPTP (ptp4l) on HPS or x86 Optional expansion via secondary bracket with 4x SMA connector (PPS/10MHz/In/Out)
Board Management	<ul style="list-style-type: none"> Intel® Max® 10 FPGA Board Management Controller Voltage level monitoring Thermal shut-down protection Over current protection on 12V input
Supported frameworks	<ul style="list-style-type: none"> Silicom Board support package Intel Application Stack Accelerator Function (ASAF) framework Silicom PacketMover (Core) DYNANIC Packet processing

Ordering Information

Ordering P/N	Notes
FB2CDG1@AGM39E-20XP2	AGM 032, 2x 8x32Gbps connector, No HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FB2CDG1@AGM32A-20XP2	AGM 032, 2x 8x32Gbps connector, 16GB HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FB2CDG1@AGM32B-20XP2	AGM 032, 2x 8x32Gbps connector, 32GB HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FB2CDG1@AGM39F-20XP2	AGM 039, 2x 8x32Gbps connector, No HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FB2CDG1@AGM39C-20XP2	AGM 039, 2x 8x32Gbps connector, 16GB HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FB2CDG1@AGM39D-20XP2	AGM 039, 2x 8x32Gbps connector, 32GB HBM2e Expansion connector: supporting 16x28Gbps for Ethernet or PCIe Gen4x16
FBF4CG@FLYN-ULN	4xQSFP28 expansion PCI adaptor with 2xARC6-16 and sideband connector 250mm
FBF4CG@FLYN-USN	4xQSFP28 expansion PCI adaptor with 2xARC6-16 and sideband connector 400mm
CBL000341	2xARC6-16 to PCIE edge PCIeGen4 x16
FB-SYNC-4S-EXT	Sync extension bracket with 4x SMA connector

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Silicom Ltd.
International Headquarters
14 Atir Yeda St.
Kfar Sava 4464323
Israel
Tel: (972)-9-764-4555

Silicom Connectivity Solutions Inc.
USA Office
6 Forest Ave, Paramus
New Jersey 07652
USA
Tel: 18004silicom (Toll Free no.)

Silicom Denmark A/S
Poppelgaardvej 11
DK-2860 Soeborg
Denmark
Phone +45 46 32 74 55
contactus@silicom.dk